

Serial No.: 10/017,318  
Atty. Docket No.: P67426US0

B<sup>1</sup>  
cond. gold wires 5a, 5b and the space including each semiconductor chip 1a, 1b and inner leads of lead frames 4a, 4b wire bonded thereto is molded by molding materials 6a, 6b so that only outer leads of lead frames 4a, 4b are exposed to both sides.--

---

On page 13, the second full paragraph beginning on line 8, has been amended to read as follows:

---

B<sup>2</sup> --Fig. 9 is a cross sectional view showing a stack chip module according to a fourth embodiment of the present invention. Referring to Fig. 9, grooves T for installing a bottom chip 20 are formed in a jig-jag form, alternating on one side and then on the other side of substrate 30 and therefore, chips 20, 22 are mounted on opposite sides of the substrate 30. Accordingly, it is possible to mount a large number of chips on both sides of the substrate 30, thereby improving the capacity of the module.--

---